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SNOS141B - AUGUST 1998-REVISED APRIL 2013

# 54ACT573 Octal Latch with Tri-State Outputs

Check for Samples: 54ACT573

#### **FEATURES**

- I<sub>CC</sub> and I<sub>OZ</sub> Reduced by 50%
- Inputs and Outputs on Opposite Sides of Package Allowing Easy Interface with Microprocessors
- Useful as Input or Output Port for Microprocessors
- Functionally Identical to 'ACT373
- Tri-State Outputs for Bus Interfacing
- Outputs Source/Sink 24 mA
- 'ACT573 has TTL-Compatible Inputs
- Standard Military Drawing (SMD)
  - 'ACT573: 5962-87664

# **Logic Symbols**

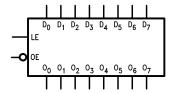


Figure 1.

### **DESCRIPTION**

The 'ACT573 is a high-speed octal latch with buffered common Latch Enable (LE) and buffered common Output Enable (OE) inputs.

The 'ACT573 is functionally identical to the 'ACT373 but has inputs and outputs on opposite sides.

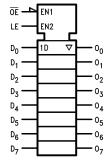


Figure 2. IEEE/IEC

Pin Names	Description
D <sub>0</sub> –D <sub>7</sub>	Data Inputs
LE	Latch Enable Input
ŌE	Tri-State Output Enable Input
O <sub>0</sub> -O <sub>7</sub>	Tri-State Latch Outputs

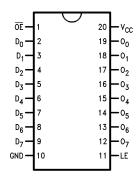
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# **Connection Diagrams**



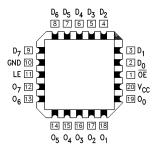


Figure 3. Pin Assignment for CDIP and CLGA

Figure 4. Pin Assignment for LCCC

# **Functional Description**

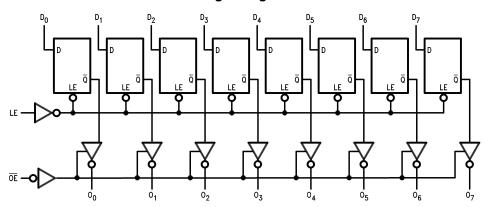
The 'ACT573 contains eight D-type latches with Tri-State output buffers. When the Latch Enable (LE) input is HIGH, data on the  $D_n$  inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The Tri-State buffers are controlled by the Output Enable ( $\overline{OE}$ ) input. When  $\overline{OE}$  is LOW, the buffers are enabled. When  $\overline{OE}$  is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.

### TRUTH TABLE(1)

	Outputs		
ŌĒ	LE	D	O <sub>n</sub>
L	Н	Н	Н
L	Н	L	L
L	L	X	O <sub>0</sub>
Н	X	X	Z

- (1) H = HIGH Voltage
  - L = LOW Voltage
  - Z = High Impedance
  - X = Immaterial
  - $O_0$  = Previous  $O_0$  before HIGH-to-LOW transition of Latch Enable

#### Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

# **ABSOLUTE MAXIMUM RATINGS**(1)(2)

Supply Voltage (V <sub>CC</sub> )		-0.5V to +7.0V
DC Input Diada Current (I.)	V <sub>I</sub> = −0.5V	−20 mA
DC Input Diode Current (I <sub>IK</sub> )	$V_I = V_{CC} + 0.5V$	+20 mA
DC Input Voltage (V <sub>I</sub> )		$-0.5V$ to $V_{CC} + 0.5V$
DC Output Diode Current (I <sub>OK</sub> )	$V_{O} = -0.5V$	−20 mA
	$V_O = V_{CC} + 0.5V$	+20 mA
DC Output Voltage (V <sub>O</sub> )		$-0.5V$ to $V_{CC} + 0.5V$
DC Output Sourceor	Sink Current (I <sub>O</sub> )	±50 mA
DC V <sub>CC</sub> or Ground Current	per Output Pin (I <sub>CC</sub> or I <sub>GND</sub> )	±50 mA
Storage Temperature (T <sub>STG</sub> )		-65°C to +150°C
Junction Temperature (T <sub>J</sub> )	CDIP	175°C

<sup>(1)</sup> Absolute Maximum Ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Texas Instruments does not recommend operation of FACT<sup>®</sup> circuits outside databook specifications.

#### RECOMMENDED OPERATING CONDITIONS

Supply Voltage (V <sub>CC</sub> )		'ACT	4.5V to 5.5V	
Input Voltage (V <sub>I</sub> )			0V to V <sub>CC</sub>	
Output Voltage (V <sub>O</sub> )			0V to V <sub>CC</sub>	
Operating Temperature (T <sub>A</sub> )		54ACT	-55°C to +125°C	
Minimum lands Edge Rate (AV//At)		V <sub>IN</sub> from 0.8V to 2.0V	405 \//	
Minimum Input Edge Rate (ΔV/Δt)	'ACT Devices	V <sub>CC</sub> @ 4.5V, 5.5V	125 mV/ns	

#### DC CHARACTERISTICS FOR 'ACT FAMILY DEVICES

			54ACT		
Symbol	Parameter	V <sub>CC</sub>	T <sub>A</sub> =	Units	Conditions
		(V)	-55°C to +125°C		
			Specified Limits		
V <sub>IH</sub>	Minimum High	4.5	2.0		V <sub>OUT</sub> = 0.1V
	Level Input Voltage	5.5	2.0	V	V <sub>OUT</sub> = 0.1V or V <sub>CC</sub> - 0.1V
V <sub>IL</sub>	Maximum Low	4.5	0.8	V or V <sub>CC</sub> -	V <sub>OUT</sub> = 0.1V
	Level Input Voltage	5.5	0.8	0.1V	
V <sub>OH</sub>	Minimum High	4.5	4.4	V	I <sub>OUT</sub> = -50 μA
	Level Output Voltage	5.5	5.4	V	
	vollage				$V_{IN} = V_{IL} \text{ or } V_{IH}^{(1)}$
		4.5	3.70	V	I <sub>OH</sub> –24 mA
		5.5	4.70		−24 mA
V <sub>OL</sub>	Maximum Low Level Output Voltage	4.5	0.1	V	I <sub>OUT</sub> = 50 μA
		5.5	0.1		
					$V_{IN} = V_{IL} \text{ or } V_{IH}^{(1)}$
		4.5	0.50	V	I <sub>OL</sub> 24 mA
		5.5	0.50		24 mA
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	±1.0	μA	$V_I = V_{CC}$ , GND

(1) All outputs loaded; thresholds on input associated with output under test.

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<sup>(2)</sup> If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.



**ISTRUMENTS** 

# **DC CHARACTERISTICS FOR 'ACT FAMILY DEVICES (continued)**

			54ACT		
Symbol	Parameter	V <sub>CC</sub>	T <sub>A</sub> =	Units	Conditions
		(V)	-55°C to +125°C Specified Limits	_	
			Opecined Emilio		
OZ	Maximum Tri-State Leakage Current	5.5	±5.0	μΑ	$V_I = V_{IL}, V_{IH}$ $V_O = V_{CC}, GND$
ССТ	Maximuml <sub>CC</sub> /Input	5.5	1.6	mA	V <sub>I</sub> = V <sub>CC</sub> - 2.1V
OLD	Minimum	5.5	50	mA	V <sub>OLD</sub> = 1.65V Max
OHD	Dynamic Output Current (2)	5.5	-50	mA	V <sub>OHD</sub> = 3.85V Min
lcc	Maximum Quiescent Supply Current	5.5	80.0	μА	V <sub>IN</sub> = V <sub>CC</sub> or GND

<sup>(2)</sup> Maximum test duration 2.0 ms, one output loaded at a time.

# **AC ELECTRICAL CHARACTERISTICS**

			54/	ACT				
		V <sub>CC</sub>	T <sub>A</sub> = -	-55°C		Fig.		
Symbol	Parameter	(V) <sup>(1)</sup>	to +1	25°C	Units	No.		
		(V)· /	C <sub>L</sub> =	C <sub>L</sub> = 50 pF		50 pF		
			Min	Max				
t <sub>PLH</sub>	Propagation Delay D <sub>m</sub> to O <sub>n</sub>	5.0	1.5	13.5	ns			
t <sub>PHL</sub>	Propagation Delay D <sub>n</sub> to O <sub>n</sub>	5.0	1.5	13.5	ns			
t <sub>PLH</sub>	Propagation Delay LE to O <sub>n</sub>	5.0	1.5	13.0	ns			
t <sub>PHL</sub>	Propagation Delay LE to O <sub>n</sub>	5.0	1.5	12.0	ns			
t <sub>PZH</sub>	Output Enable Time	5.0	1.5	11.5	ns			
t <sub>PZL</sub>	Output Enable Time	5.0	1.5	11.0	ns			
t <sub>PHZ</sub>	Output Disable Time	5.0	1.5	13.5	ns			
t <sub>PLZ</sub>	Output Disable Time	5.0	1.5	10.5	ns			

<sup>(1)</sup> Voltage Range 5.0 is 5.0V ±0.5V

### **AC OPERATING REQUIREMENTS**

Symbol	Parameter	V <sub>CC</sub> (V) <sup>(1)</sup>	54ACT  T <sub>A</sub> = -55°C  to +125°C  C <sub>L</sub> = 50 pF  Specified Minimum	Units	Fig. No.
t <sub>s</sub>	Setup Time, HIGH or LOW D <sub>n</sub> to LE	5.0	4.5	ns	
t <sub>h</sub>	Hold Time, HIGH or LOW D <sub>n</sub> to LE	5.0	1.0	ns	
t <sub>w</sub>	LE Pulse Width, HIGH	5.0	5.0	ns	

<sup>(1)</sup> Voltage Range 5.0 is 5.0V ±0.5V

## **CAPACITANCE**

Symbol	Parameter	Тур	Units	Conditions
C <sub>IN</sub>	Input Capacitance	5.0	pF	V <sub>CC</sub> = OPEN
C <sub>PD</sub>	Power Dissipation Capacitance	25.0	pF	V <sub>CC</sub> = 5.0V

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# **REVISION HISTORY**

CI	Changes from Revision A (April 2013) to Revision B				
•	Changed layout of National Data Sheet to TI format	4			

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